Application No. 10/508,955 Amendment dated **December 17, 2007** First Preliminary Amendment 2

Docket No.: 80653(47762)

## **AMENDMENTS TO THE CLAIMS**

Claim 1 (Currently Amended): A method for applying a hot melt adhesive in a melted state to a surface of a substrate, the method comprising the steps of:

preparing a hot melt adhesive, which is a urethane reactive hot melt adhesive and melts in a temperature range of 100 to 130°C;

conveying a substrate which is a wood board at a predetermined speed;

rotating an applicator roller, which is covered with the hot melt adhesive in a melted state supplied from an interface of the applicator roller and a metering-roller, in the direction which the substrate is moved on a conveyer and at a circumferential speed at least 20% slower or at least 20% faster than the predetermined speed of the substrate to cause the roller to slip, wherein the substrate is covered with the hot melt adhesive in a melted state supplied from a pool of the hot melt adhesive located between the applicator roller and a metering roller via an interface of the rollers; and

contacting the upper surface of the substrate and the applicator roller to form an adhesive layer on the upper surface of the substrate from the hot melt adhesive.

Claim 2 (Original): The method for applying a hot melt adhesive to a surface of a substrate according to claim 1, wherein the adhesive layer is formed by applying a plurality of coatings of the hot melt adhesive.

Claim 3 (Original): The method for applying a hot melt adhesive to a surface of a substrate according to claim 1, wherein the circumferential speed of the applicator roller is set to be less than the predetermined speed at which the substrate is conveyed, with a speed reduction

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ratio ranging from 20% to 80% and equal to (conveying speed of substrate-circumferential

speed of applicator roller) x 100 / conveying speed of substrate.

Claim 4 (Original): A substrate obtained by the method for applying a hot melt

adhesive to a surface of a substrate according to claims 1 to 3.

Claim 5-9 (Canceled)

Claim 10 (Currently Amended): A method for producing a laminated object, the

method comprising the steps of:

conveying a substrate which is a wood board at a predeter nined speed;

contacting the upper surface of the substrate and the an applicator roller;

rotating an the applicator roller covered with hot melt adhesive in a melted state which is

supplied from a pool of the hot melt adhesive located between the applicator roller and a

metering roller at an interface of the applicator roller and a metering roller, at a circumferential

speed at least 20% slower or at least 20% faster than the predetermined speed at which the

substrate is conveyed to cause it to slip; and

applying a laminate on the adhesive layer.

Claim 11 (Original): The method of producing a laminated object according to claim

10, wherein the adhesive is applied by a plurality of applicator rollers.

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Claim 12 (Original): The method of producing a laminated object according to claim 10, wherein the substrate is a wood board, the adhesive is urethane reactive hot melt adhesive, and the laminate is a film or a decorative paper.

Claim 13-14 (Canceled).

Claim 15 (Previously Presented): The method for applying the hot melt adhesive to the surface of the substrate according to claim 1, wherein a clearance between the applicator roller and a backing roller is 99% to 95% of the thickness of the substrate.

Claim 16 (Previously Presented): The method for applying the hot melt adhesive to the surface of the substrate according to claim 1, wherein the urethane reactive hot melt adhesive which melts in a temperature range of 100 to 130°C has a viscosity of 1,000 to 30,000 mPa·s.

Claims 17-18 (Canceled).